Statement of Materials, Construction

LEAD-FREE -- 16L QFN -- TABLE OF MATERIAL DECLARATION								
No.	Component Name	Material Name	Component Weight (grams)	Materials Analysis (Element/Compound)	CAS Number	Material Mass (grams)	Material Weight % (of Total Pkg.)	Material Weight % (of Component)
1	Leadframe	Copper Alloy (with silver plating)	0.01750	Cu	7440-50-8	0.01699	26.60	97.10
				Fe	7439-89-6	0.00044	0.68	2.50
				P	7723-14-0	0.00002	0.03	0.10
				Zn	7440-66-6	0.00002	0.03	0.10
				Silver Plating	7440-22-4	0.00004	0.05	0.20
2	Die	Silicon Chip	0.00172	Si	7440-21-3	0.00172	2.69	99.99
3	Die Attach Material	Conductive Epoxy	0.00040	Silver (Ag)	7440-22-4	0.00029	0.45	73.50
				Epoxy Resin A	9003-36-5	0.00004	0.06	10.00
				Epoxy Resin B	5026-74-4	0.00002	0.03	5.00
				Hardener A	Proprietary	0.00003	0.04	7.00
				Hardener B	Proprietary	0.00001	0.02	3.00
				Elastomer	Proprietary	0.00001	0.01	1.50
4	Wire	Gold	0.00019	Au	7440-57-5	0.00019	0.29	99.99
5	Lead Finish	Tin	0.00120	Sn	7440-31-5	0.00120	1.88	100
6	Encapsulation	Epoxy Resin	0.04288	Fused Silica	60676-86-0	0.04017	62.90	93.70
				Epoxy Resin	Proprietary	0.00129	2.01	3.00
				Phenol Resin	Proprietary	0.00129	2.01	3.00
				Carbon Black	1333-86-4	0.00013	0.20	0.30
Total Package Weight =			0.06387					

Note: Component Weight based on assembly of generic parts.

Conclusion:

The analysis table above shows that this package meets the following RoHS requirements for EACH PACKAGE COMPONENT (mold compound, lead frame, etc.)

	Maximum Allowable Limit (ppm)	Maximum Allowable Limit (wt %)
Lead	1000 ppm	0.10%
Mercury	1000 ppm	0.10%
Cadmium	100 ppm	0.01%
Hexavalent Chromium	1000 ppm	0.10%
Polybrominated Biphenyls (PBB)	1000 ppm	0.10%
Polybrominated Biphenylethers (PBDE)	1000 ppm	0.10%